



Figure 1.2: CLIC basic layout for 3 TeV system (top) and for 500 GeV system (bottom)

Point and the ability to protect the machine against damage while still providing a high availability. All these issues are being demonstrated by a sophisticated R&D program having established an international collaboration of 41 institutions and many facilities around the world, exploring the technological frontiers to demonstrate the CLIC technology feasibility. Another very important issue is the generation of the nanometer beam sizes at the IP and the chromatic correction performed at the Final Focus System (FFS).